

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Xiang Dai et al.	Examiner:	James M. Mitchell
Serial No.:	10/612,663	Group Art Unit:	2813
Filed:	July 2, 2003	Docket No.:	200308566-1
Title:	SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE HAVING A SOLDER COLUMN ARRAY		

AMENDMENT AND RESPONSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Amendment and Response is in reply to the Non-Final Office Action mailed February 23, 2007. Please amend the above-identified patent application as follows: